



#### COMPLEMENTARY PAIR ENHANCEMENT MODE MOSFET

### **Product Summary**

Device	BV <sub>DSS</sub>	R <sub>DS(ON)</sub> Max	I <sub>D</sub> Max T <sub>A</sub> = +25°C
Q1	20V	$35m\Omega$ @ V <sub>GS</sub> = 4.5V	4.6A
N-Channel	N-Channel	43mΩ @ V <sub>GS</sub> = 2.5V	4.1A
Q2	-20V	$75m\Omega$ @ V <sub>GS</sub> = -4.5V	-3.1A
P-Channel	-20V	110mΩ @ V <sub>GS</sub> = -2.5V	-2.6A

#### **Features**

- PCB Footprint of 4mm<sup>2</sup>
- Low On-Resistance
- Low Input Capacitance
- Low Profile, 0.6mm Maximum Height
- Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)
- Halogen- and Antimony-Free. "Green" Device (Note 3)
- The DMC2053UFDBQ is suitable for automotive applications requiring specific change control; This part is AEC-Q101 qualified, PPAP capable, and manufactured in IATF 16949 certified facilities.

https://www.diodes.com/quality/product-definitions/

## **Description and Applications**

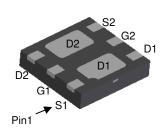
This MOSFET is designed to minimize the on-state resistance (R<sub>DS(ON)</sub>) yet maintain superior switching performance, which makes it ideal for high-efficiency power management applications.

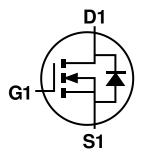
- Load switches
- Power management functions
- Portable power adaptors

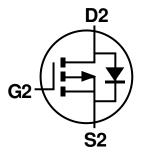
## **Mechanical Data**

- Package: U-DFN2020-6
- Package Material: Molded Plastic, "Green" Molding Compound.
   UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Finish NiPdAu over Copper Lead-Frame. Solderable per MIL-STD-202, Method 208 (4)
- Terminals Connections: See Diagram Below
- Weight: 0.0065 grams (Approximate)

#### U-DFN2020-6 (Type B)







N-Channel MOSFET

P-Channel MOSFET

**Bottom View** 

Internal Schematic

### **Ordering Information** (Note 4)

Part Number	Paskaga	Pac	Packing			
Part Number	Package	Qty.	Carrier			
DMC2053UFDBQ-7	U-DFN2020-6 (Type B)	3,000	Tape & Reel			
DMC2053UFDBQ-13	U-DFN2020-6 (Type B)	10,000	Tape & Reel			

Notes:

- 1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS), 2011/65/EU (RoHS 2) & 2015/863/EU (RoHS 3) compliant.
- 2. See https://www.diodes.com/quality/lead-free/ for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
- 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
- 4. For packaging details, go to our website at https://www.diodes.com/design/support/packaging/diodes-packaging/.



# **Marking Information**

## U-DFN2020-6 (Type B)



H4 = Product Type Marking Code YWX = Date Code Marking Y = Year (ex: 3 = 2023) W = Week (ex: a = Week 27; z Represents Week 52 and 53) X = Internal Code (ex: U = Monday)

Date Code Key

Year	2020	-	2023	2024	2025	2026	2027	2028	2029	2030	2031	2032
Code	0	-	3	4	5	6	7	8	9	0	1	2

Week	1-26	27-52	53
Code	A-Z	a-z	Z

Internal Code	Sun	Mon	Tue	Wed	Thu	Fri	Sat
Code	T	U	V	W	Χ	Υ	Z



## Maximum Ratings (@ TA = +25°C, unless otherwise specified.)

Characteristic	Symbol	Q1 N-CHANNEL	Q2 P-CHANNEL	Unit		
Drain-Source Voltage			V <sub>DSS</sub>	20	-20	V
Gate-Source Voltage	Vgss	±12	±12	V		
Continuous Drain Current (Note 6) Vgs = 4.5V	Steady State	T <sub>A</sub> = +25°C T <sub>A</sub> = +70°C	lD	4.6 3.7	-3.1 -2.5	А
Maximum Continuous Body Diode Forward Curi	ls	1.1	-1.05	Α		
Pulsed Drain Current (10μs Pulse, Duty Cycle =	IDM	24	-15	Α		

# **Thermal Characteristics**

Characteristic	Symbol	Value	Unit	
Total Power Dissipation (Note 5)	$T_A = +25^{\circ}C$	PD	0.82	W
Thermal Resistance, Junction to Ambient (Note 5)	Steady State	Rөja	153	°C/W
Total Power Dissipation (Note 6)	T <sub>A</sub> = +25°C	PD	1.14	W
Thermal Resistance, Junction to Ambient (Note 6)	Steady State	Rөja	110	°C/W
Operating and Storage Temperature Range		TJ, TSTG	-55 to +150	°C

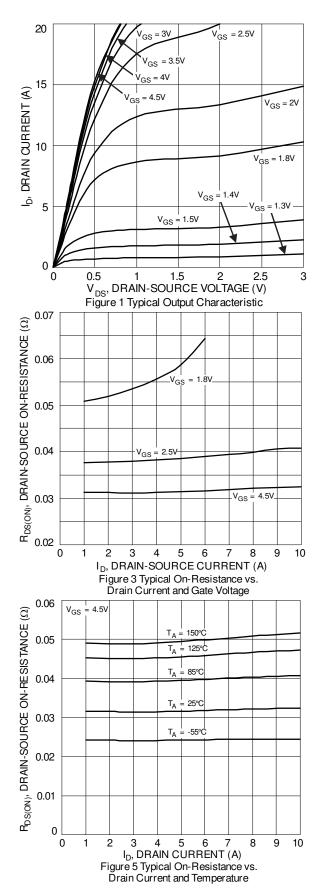
# Electrical Characteristics Q1 N-CHANNEL (@ T<sub>A</sub> = +25°C, unless otherwise specified.)

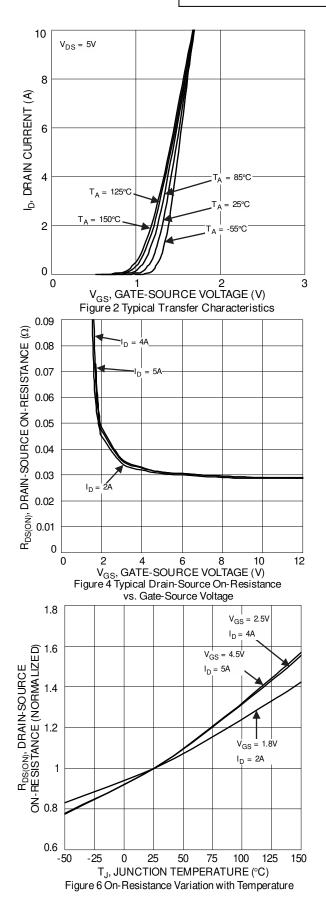
`						
Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition
OFF CHARACTERISTICS (Note 7)						
Drain-Source Breakdown Voltage	BV <sub>DSS</sub>	20	_	_	٧	$V_{GS} = 0V, I_D = 250\mu A$
Zero Gate Voltage Drain Current T <sub>J</sub> = +25°C	IDSS		1	1.0	μΑ	V <sub>DS</sub> = 20V, V <sub>GS</sub> = 0V
Gate-Source Leakage	Igss	_	_	±100	nA	$V_{GS} = \pm 12V$ , $V_{DS} = 0V$
ON CHARACTERISTICS (Note 7)						
Gate Threshold Voltage	V <sub>GS(TH)</sub>	0.4	_	1.0	V	$V_{DS} = V_{GS}$ , $I_D = 250 \mu A$
			24	35		$V_{GS} = 4.5V, I_D = 5A$
Static Drain-Source On-Resistance	RDS(ON)	_	30	43	mΩ	$V_{GS} = 2.5V, I_{D} = 4A$
			44	56		$V_{GS} = 1.8V, I_D = 2A$
Diode Forward Voltage	V <sub>SD</sub>	_	0.7	1.2	V	V <sub>G</sub> S = 0V, I <sub>S</sub> = 1A
DYNAMIC CHARACTERISTICS (Note 8)		•				
Input Capacitance	C <sub>iss</sub>	_	369	_		
Output Capacitance	Coss	_	54	_	pF	$V_{DS} = 10V, V_{GS} = 0V,$ f = 1.0MHz
Reverse Transfer Capacitance	C <sub>rss</sub>	_	32	_		
Gate Resistance	Rg	_	4.1	_	Ω	$V_{DS} = 0V$ , $V_{GS} = 0V$ , $f = 1MHz$
Total Gate Charge (VGS = 4.5V)	Qg	_	3.6	_		
Total Gate Charge (VGS = 10V)	Qg	_	7.7	_	nC	V <sub>DS</sub> = 10V. I <sub>D</sub> = 6A
Gate-Source Charge	Qgs	_	0.4	_	110	VDS = 10V, ID = 6A
Gate-Drain Charge	$Q_{gd}$	_	1.0	_		
Turn-On Delay Time	td(ON)	_	2.6	_		
Turn-On Rise Time	t <sub>R</sub>	_	3.0	_	20	$V_{DS} = 10V, V_{GS} = 4.5V,$
Turn-Off Delay Time	t <sub>D(OFF)</sub>	_	12.5	_	ns	$R_g = 6\Omega$ , $R_L = 10\Omega$ , $I_D = 6A$
Turn-Off Fall Time	t⊧	_	3.6	_		
Reverse Recovery Time	trr	_	6.0	_	ns	I <sub>F</sub> = 1A, di/dt = 100A/μs
Reverse Recovery Charge	Qrr		0.9	_	nC	I <sub>F</sub> = 1A, di/dt = 100A/μs

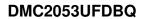
 Device mounted on FR-4 substrate PCB, 2oz copper, with minimum recommended pad layout.
 Device mounted on FR-4 substrate PCB, 2oz copper, with 1inch square copper plate.
 Short duration pulse test used to minimize self-heating effect.
 Guaranteed by design. Not subject to product testing. Notes:



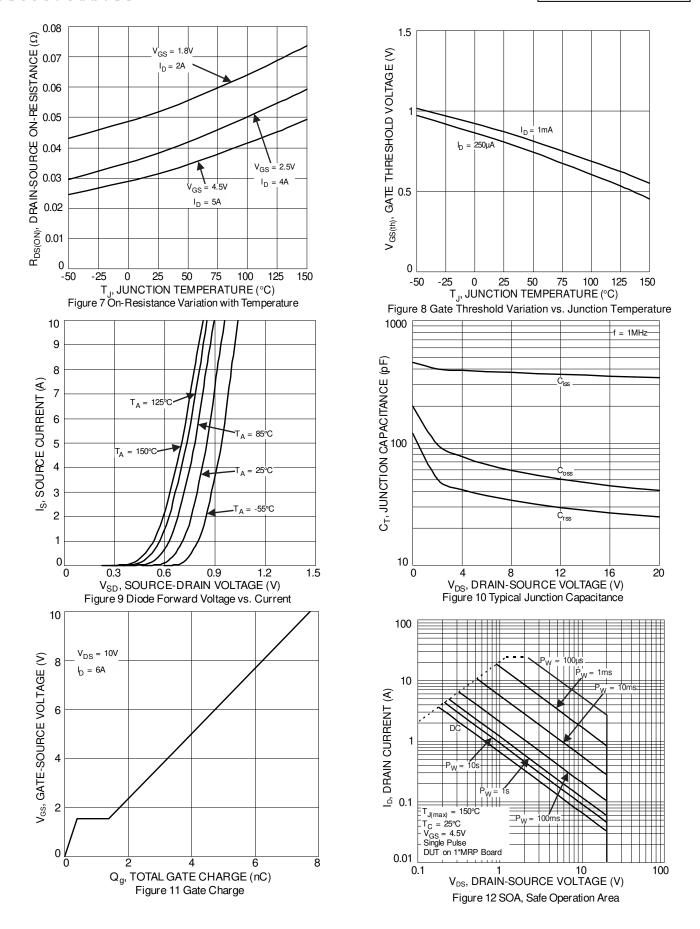




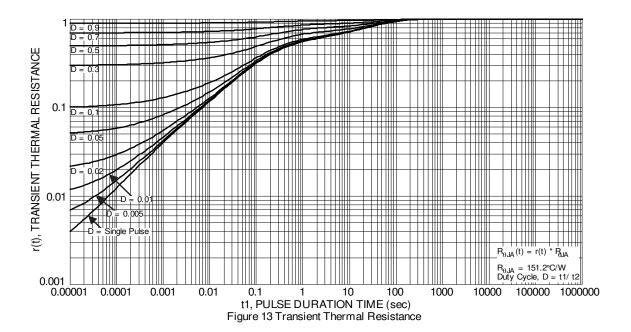














# Electrical Characteristics Q2 P-CHANNEL (@ TA = +25°C, unless otherwise specified.)

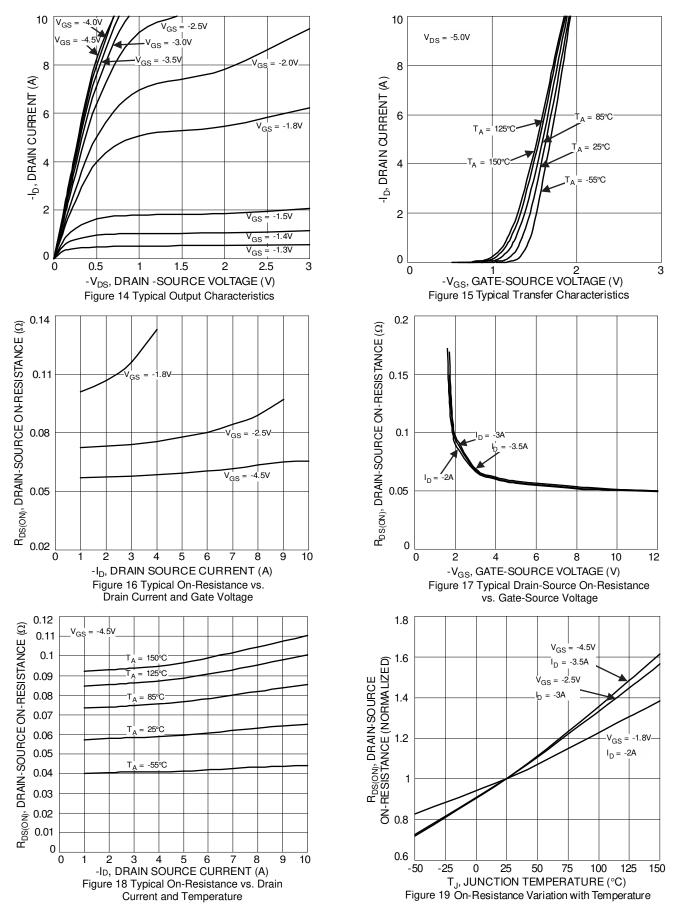
Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition				
OFF CHARACTERISTICS (Note 7)						•				
Drain-Source Breakdown Voltage	BV <sub>DSS</sub>	-20	_	_	V	$V_{GS} = 0V, I_{D} = -250\mu A$				
Zero Gate Voltage Drain Current T <sub>J</sub> = +25°C	I <sub>DSS</sub>	_	_	-1.0	μΑ	$V_{DS} = -20V, V_{GS} = 0V$				
Gate-Source Leakage	Igss	_	_	±100	nA	$V_{GS} = \pm 12V$ , $V_{DS} = 0V$				
ON CHARACTERISTICS (Note 7)										
Gate Threshold Voltage	V <sub>GS(TH)</sub>	-0.45	_	-1.0	V	$V_{DS} = V_{GS}$ , $I_D = -250\mu A$				
		_	57	75		Vgs = -4.5V, ID = -3.5A				
Static Drain-Source On-Resistance	RDS(ON)	_	73	110	mΩ	Vgs = -2.5V, ID = -3.0A				
		_	105	168		VGS = -1.8V, ID = -2.0A				
Diode Forward Voltage	V <sub>SD</sub>	_	-0.7	-1.2	V	VGS = 0V, IS = -1.0A				
DYNAMIC CHARACTERISTICS (Note 8)		•				•				
Input Capacitance	Ciss	_	440	_	pF					
Output Capacitance	Coss	_	60	_	pF	V <sub>DS</sub> = -10V, V <sub>GS</sub> = 0V, f = 1.0MHz				
Reverse Transfer Capacitance	Crss	_	48	_	pF	71 - 1.0WH12				
Gate Resistance	Rg	_	8.5	_	Ω	$V_{DS} = 0V$ , $V_{GS} = 0V$ , $f = 1MHz$				
Total Gate Charge (V <sub>GS</sub> = -4.5V)		_	5.9	_	nC					
Total Gate Charge (V <sub>GS</sub> = -8V)	Qg	_	12.7	_	nC	],, ,,, ,,,				
Gate-Source Charge	Q <sub>gs</sub>	_	0.6	_	nC	$V_{DS} = -4V$ , $I_{D} = -3.5A$				
Gate-Drain Charge	$Q_{gd}$	_	2.1	_	nC	7				
Turn-On Delay Time	tD(ON)	_	3.2	_	ns					
Turn-On Rise Time	tr	_	7.8	_	ns	$V_{DS} = -4V, V_{GS} = -4.5V,$				
Turn-Off Delay Time	tD(OFF)	_	31	_	ns	$R_L = 4\Omega$ , $R_g = 6\Omega$				
Turn-Off Fall Time	tF	_	18	_	ns					
Body Diode Reverse Recovery Time	trr	_	10.5	_	ns	Is = -2.0A, dI/dt = 100A/µs				
Body Diode Reverse Recovery Charge	Qrr	_	3.0	_	nC	Is = -2.0A, dI/dt = 100A/μs				

Notes:

<sup>7.</sup> Short duration pulse test used to minimize self-heating effect.

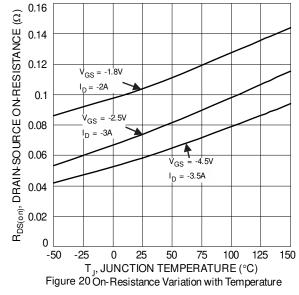
<sup>8.</sup> Guaranteed by design. Not subject to product testing.

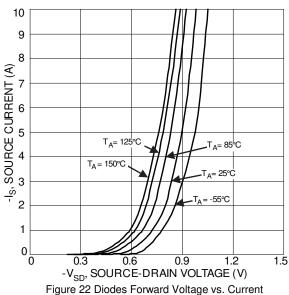


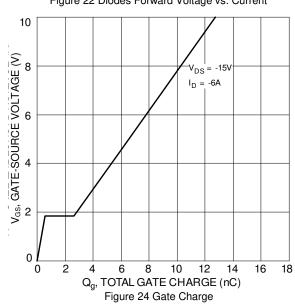


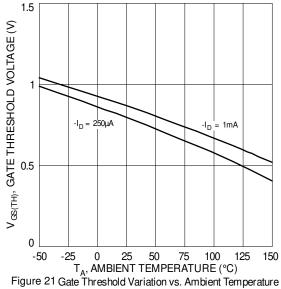


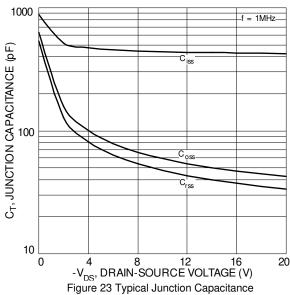


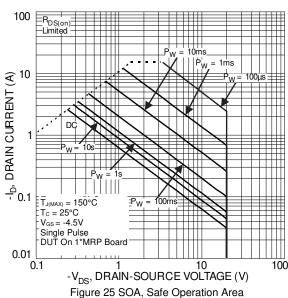










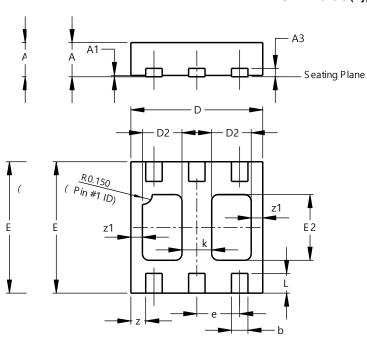




# **Package Outline Dimensions**

Please see http://www.diodes.com/package-outlines.html for the latest version.

### U-DFN2020-6 (Type B)

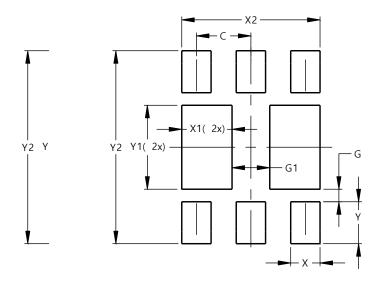


U-DFN2020-6 Type B						
Dim	Min	Max	Тур			
Α	0.545	0.605	0.575			
A1	0.00	0.05	0.02			
A3	-	-	0.13			
b	0.20	0.30	0.25			
D	1.95	2.075	2.00			
D2	0.50	0.70	0.60			
е	-	-	0.65			
E	1.95	2.075	2.00			
E2	0.90	1.10	1.00			
k	1	-	0.45			
L	0.25	0.35	0.30			
Z	-	-	0.225			
z1	-	-	0.175			
All Dimensions in mm						

## **Suggested Pad Layout**

Please see http://www.diodes.com/package-outlines.html for the latest version.

#### U-DFN2020-6 (Type B)



Dimensions	Value
פווטופווסוווט	(in mm)
C	0.650
G	0.150
G1	0.450
Х	0.350
X1	0.600
X2	1.650
Υ	0.500
Y1	1.000
Y2	2.300



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